



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-11-28
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacopello	Representative Title	ADG MD Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ESDA6V1-5SC6	8BWB*ASX6V15	A	Z8GA	2016-11-28
Amount		UoM	Unit type	ST ECOPACK Grade
14.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy		
Not Applicable ; if coating is used o	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	2.9 - 1.625 - 1.175	6	gull wing	
Comment	Package: SOT 23 - 6L			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	88WB*ASX6V15					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon Die	Other inorganic materials	0.165	mg	supplier	die	Silicon (Si)	7440-21-3		0.163	mg	987879	11643
Silicon Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.001	mg	6061	71
Silicon Die				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.001	mg	6061	71
Lead-frame	Copper & its alloys	6.355	mg	Supplier	alloy	Copper(CU)	7440-50-8		6.041	mg	950590	431500
Lead-frame				Supplier	alloy	Iron(Fe)	7439-89-6		0.146	mg	22974	10429
Lead-frame				Supplier	alloy	Iron Phosphide(FeP)	26508-33-8		0.005	mg	787	357
Lead-frame				Supplier	alloy	Zinc(Zn)	7440-66-6		0.008	mg	1259	571
Lead-frame				Supplier	metallization	Silver(Ag)	7440-22-4		0.155	mg	24390	11071
Die attach	Other inorganic materials	0.103	mg	supplier	glue	Silver(Ag)	7440-22-4		0.076	mg	737864	5429
Die attach				supplier	glue	Acrylate monomer	Proprietary		0.015	mg	145631	1071
Die attach				supplier	glue	Acrylate oligomer	Proprietary		0.008	mg	77670	571
Die attach				supplier	glue	Bismaleimide resin	Proprietary		0.003	mg	29126	214
Die attach				supplier	glue	Epoxy resin	Proprietary		0.001	mg	9709	71
Bonding wire	Other inorganic materials	0.016	mg	supplier	wire	Copper(CU)	7440-50-8		0.016	mg	1000000	1143
Encapsulation	Other inorganic materials	7.159	mg	supplier	Molding compound	Silica Fused	60676-86-0		6.206	mg	866881	443286
Encapsulation				supplier	Molding compound	Epoxy Resin	Proprietary		0.573	mg	80039	40929
Encapsulation				supplier	Molding compound	Phenol Resin	Proprietary		0.358	mg	50007	25571
Encapsulation				supplier	Molding compound	Carbon Black	1333-86-4		0.022	mg	3073	1571
Connections coating	Solder	0.202	mg	supplier	solder alloy	Tin(Sn)	7440-31-5		0.202	mg	1000000	14429